



Material Content Data Sheet



Sales Product Name		BSC0904NSI		Issued		27. September 2017		
MA#		MA001015226						
Package		PG-TDSON-8-6		Weight*		118.04 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.285	0.24	0.24	2410	2410
leadframe	non noble metal	iron	7439-89-6	0.038	0.03		320	
	inorganic material	phosphorus	7723-14-0	0.011	0.01		96	
	non noble metal	copper	7440-50-8	37.762	31.99	32.03	319898	320314
wire	noble metal	gold	7440-57-5	0.047	0.04	0.04	394	394
encapsulation	organic material	carbon black	1333-86-4	0.088	0.07		748	
	plastics	epoxy resin	-	6.268	5.31		53097	
	inorganic material	silicondioxide	60676-86-0	37.783	32.01	37.39	320080	373925
leadfinish	non noble metal	tin	7440-31-5	1.470	1.25	1.25	12451	12451
plating	noble metal	silver	7440-22-4	0.166	0.14	0.14	1402	1402
solder	noble metal	silver	7440-22-4	0.012	0.01		100	
	non noble metal	tin	7440-31-5	0.009	0.01		80	
	non noble metal	lead	7439-92-1	0.450	0.38	0.40	3812	3992
heatspreader	non noble metal	iron	7439-89-6	0.011	0.01		96	
	inorganic material	phosphorus	7723-14-0	0.003	0.00		29	
	non noble metal	copper	7440-50-8	11.320	9.59	9.60	95898	96023
heat sink CLIP	non noble metal	iron	7439-89-6	0.022	0.02		189	
	inorganic material	phosphorus	7723-14-0	0.007	0.01		57	
	non noble metal	copper	7440-50-8	22.292	18.88	18.91	188843	189089
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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